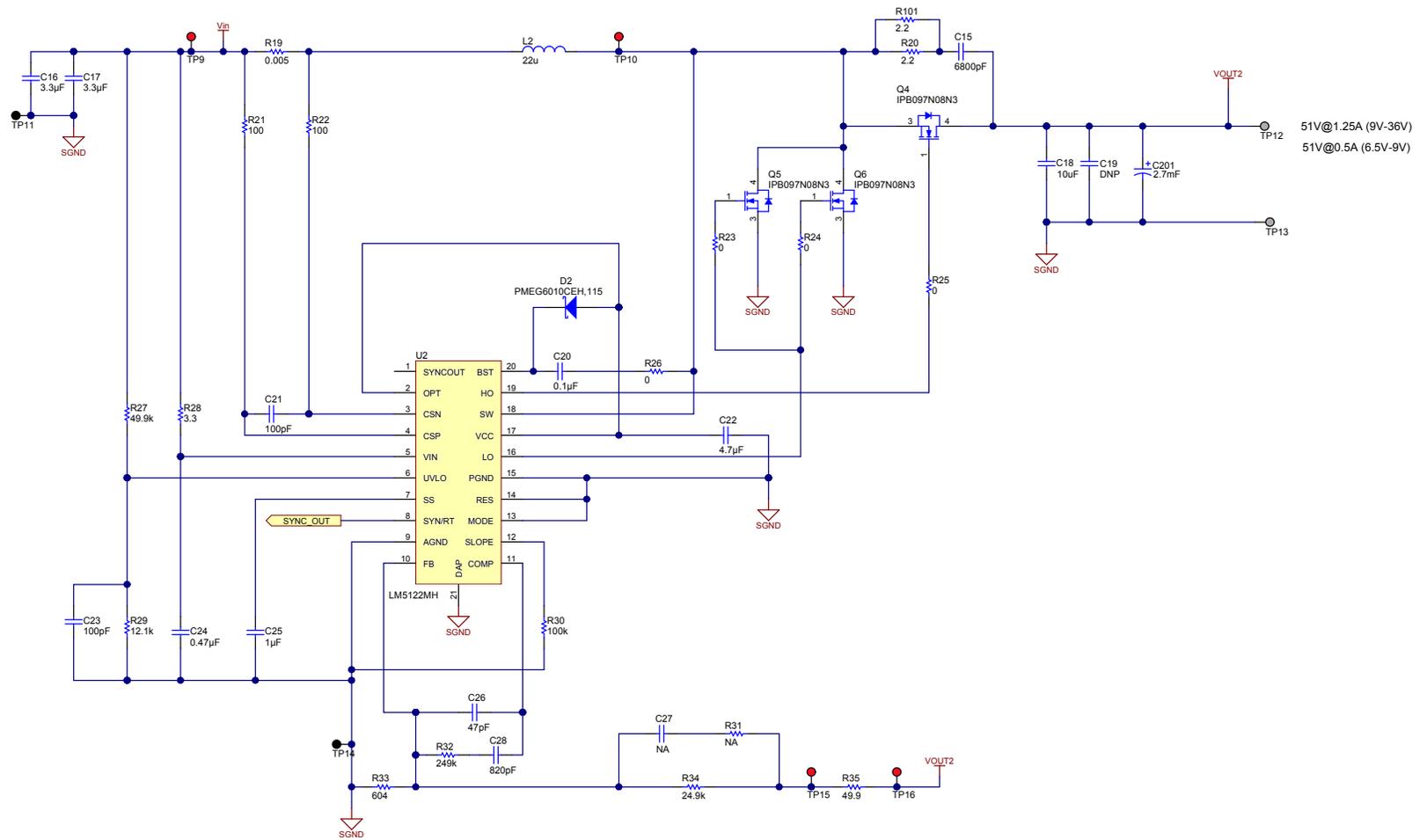


6.5-36V

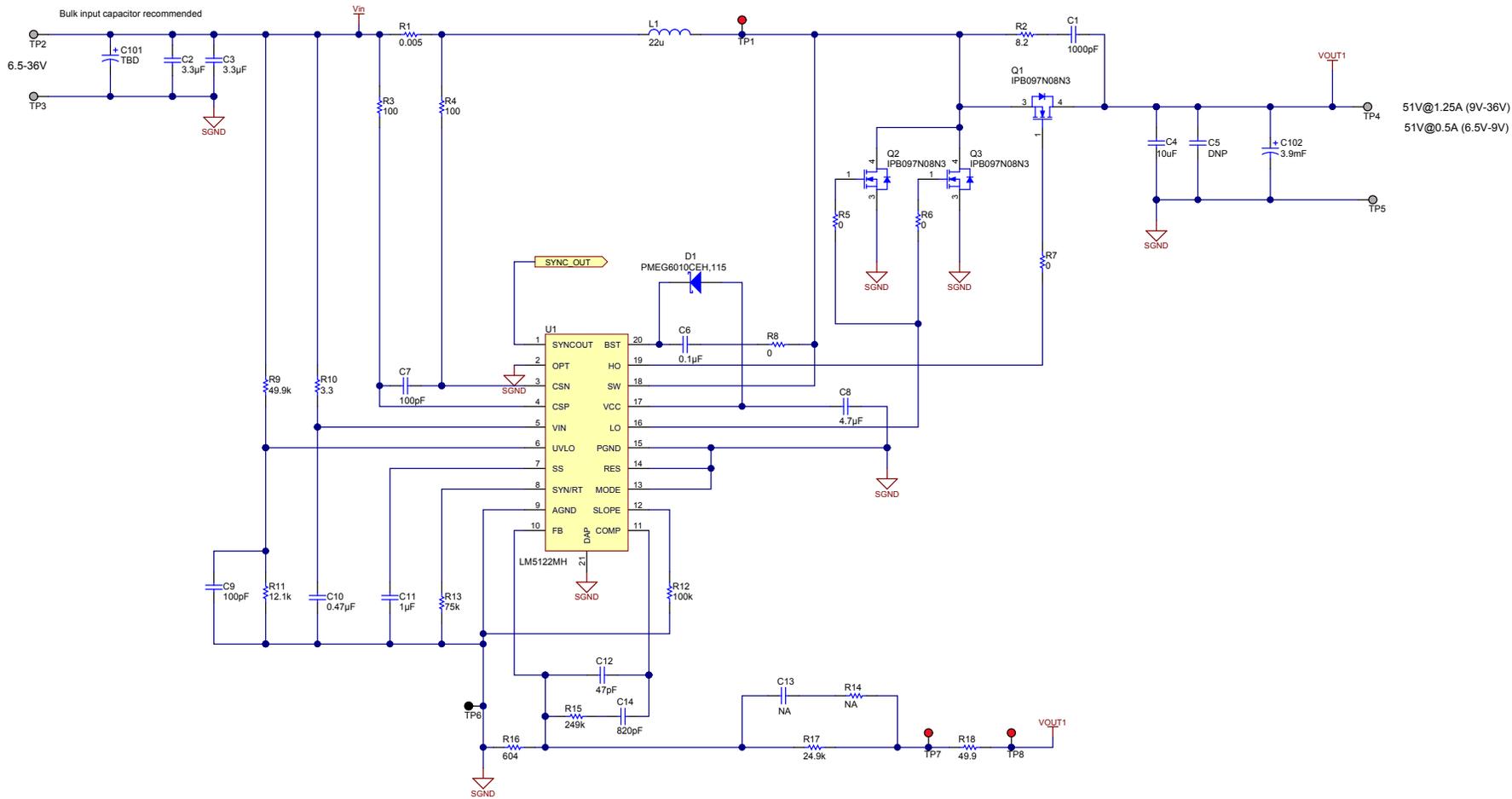


Notes:

- RefDes>100 connected externally
- TBD = "TO BE DEFINED"
- DNP = "DO NOT POPULATE"
- R35 for test purposes only
- the bottom of the board should be thermally connected to a heatsink
- input bulk capacitor needed for startup at Vin<9V

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Number: PMP8532	Rev: SCH	Designed for: Public Release	Mod. Date: 3/19/2013
SVN Rev: Not in version control	Assembly Variant: 001	Project Title: Change in menu Project/Project Options/Parameter	Sheet: 1 of 1
Drawn By:	Engineer: F. Mueller	File: PMP8532_RevC_2_SchDoc	Size: B
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Notes:

- RefDes>100 connected externally
- TBD = "TO BE DEFINED"
- DNP = "DO NOT POPULATE"
- R18 for test purposes only
- the bottom of the board should be thermally connected to a heatsink
- input bulk capacitor needed for startup at Vin<9V

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